

6. (Amended) The IBC apparatus of claim 1 further comprising at least one slit valve located proximate the transfer position.
7. (Amended) The IBC apparatus of claim 1 wherein the actuator comprises a spindle assembly for retaining the substrate and rotating the substrate, and a linear actuator for raising and lowering the spindle assembly.
8. (Amended) The IBC apparatus of claim 7 wherein the spindle assembly comprises a vacuum chuck.
9. (Amended) The IBC apparatus of claim 1 wherein the plurality of etchant dispense nozzles are coupled to at least one etchant dispensing arm assembly positioned proximate the etch position to apply etchant to the front side and backside of the substrate.
10. (Amended) The IBC apparatus of claim 9 wherein the etchant is applied to an edge exclusion zone of the substrate.
11. (Amended) The IBC apparatus of claim 9 wherein the at least one etchant dispensing arm assembly is rotatable into a position near the substrate and away from the substrate.
12. (Amended) The IBC apparatus of claim 11 wherein the at least one etchant dispensing arm assembly comprises a plurality of etchant dispensing arm assemblies.
13. (Amended) The IBC apparatus of claim 12 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled for simultaneously rotating the

plurality of etchant dispensing arm assemblies into a position near the substrate and away from the substrate.

Please cancel claims 14-22:

14. (Canceled) A method for etching electroplated material from a substrate within an integrated bevel cleaning (IBC) apparatus, comprising:

- introducing the substrate into a transfer position within the IBC apparatus;
- moving the substrate to a rinse position within the IBC apparatus;
- rinsing the substrate in the rinse position within the IBC apparatus;
- moving the substrate to an etch position within the IBC apparatus; and
- etching material from the substrate in the etch position within the IBC apparatus.

15. (Canceled) The method of claim 14 wherein the substrate is rotated while in the rinse position and the etch position.

16. (Canceled) The method of claim 14 wherein the introducing step further comprises opening at least one of a plurality of slit valves.

17. (Canceled) The method of claim 14 wherein the step of etching comprises positioning at least one etchant dispenser arm proximate the substrate.

18. (Canceled) The method of claim 17 wherein the at least one etchant dispenser arm comprises three etchant dispenser arms that are coupled to a single motor that imparts rotation in all three etchant dispenser arm simultaneously.

19. (Canceled) A system for processing substrates comprising:
- a loading station having at least one first chamber;
  - a process region having at least one second chamber;
  - an integrated bevel cleaning (IBC) apparatus comprising a transfer position through which a substrate can be passed from said load station to said process region without processing being performed in said IBC apparatus.
20. (Canceled) The system of claim 19 wherein said at least one second chamber is an electroplating chamber.
21. (Canceled) The system of claim 19 wherein said load station comprises a first substrate handler and said second process region comprises a second substrate handler.
22. (Canceled) The system of claim 19 wherein said IBC apparatus performs edge bead removal and substrate cleaning.

Please add the following new claims:

23. (New) The IBC apparatus of claim 13 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled to a single motor for simultaneously rotating the plurality of etchant dispensing arm assemblies.
24. (New) An integrated bevel cleaning (IBC) apparatus, comprising:
- a transfer position where a substrate is positioned;
  - a processing position wherein at least one of rinsing and etching is conducted on the substrate;

an actuator for positioning the substrate in the transfer position and the processing position; and

a plurality of cooperatively movable etchant dispense nozzles configured to dispense an etchant onto the front side and backside of the substrate.

25. (New) The IBC apparatus of claim 24 further comprising a substrate centering hoop for supporting the substrate in the transfer position.

26. (New) The IBC apparatus of claim 25 further comprising a substrate centering hoop rinsing nozzle.

27. (New) The IBC apparatus of claim 24 further comprising at least one rinsing nozzle located proximate the processing position for rinsing at least an edge region of the substrate.

28. (New) The IBC apparatus of claim 27 wherein the at least one rinsing nozzle comprises a plurality of rinsing nozzles positioned to rinse the front side and backside of the substrate.

29. (New) The IBC apparatus of claim 24 further comprising at least one slit valve located proximate the transfer position.

30. (New) The IBC apparatus of claim 24 wherein the actuator comprises a spindle assembly for retaining the substrate and rotating the substrate, and a linear actuator for raising and lowering the spindle assembly.

31. (New) The IBC apparatus of claim 30 wherein the spindle assembly comprises a vacuum chuck.

32. (New) The IBC apparatus of claim 24 wherein the plurality of etchant dispense nozzles are coupled to at least one etchant dispensing arm assembly positioned proximate the processing position to apply etchant to the front side and backside of the substrate.

33. (New) The IBC apparatus of claim 32 wherein the etchant is applied to an edge exclusion zone of the substrate.

34. (New) The IBC apparatus of claim 32 wherein the at least one etchant dispensing arm assembly is rotatable into a position near the substrate and away from the substrate.

35. (New) The IBC apparatus of claim 34 wherein the at least one etchant dispensing arm assembly comprises a plurality of etchant dispensing arm assemblies.

36. (New) The IBC apparatus of claim 35 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled for simultaneously rotating the plurality of etchant dispensing arm assemblies into a position near the substrate and away from the substrate.

37. (New) The IBC apparatus of claim 36 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled to a single motor for simultaneously rotating the plurality of etchant dispensing arm assemblies.